

07-07-2003



Form PTO-1595

(Rev. 10/02)

OMB No. 0651-0027 (exp. 6/30/2005)

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Akio NISHIDA  
Yasuko YOSHIDA  
Shuji IKEDA

2. Name and address of receiving party(ies)

Name: HITACHI, LTD.

Address: 6, Kanda Surugadai 4-chome  
Chiyoda-ku, Tokyo, JAPANAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other \_\_\_\_\_Additional name(s) & address(es) attached? ☐ Yes ☒ No

Execution Date: February 17, 2003 and February 20, 2003.

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No.(s)

10/363,055

B. Patent Registration No.(s)

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Antonelli, Terry, Stout &amp; Kraus, LLP

Internal Address:

1300 North Seventeenth Street  
Suite 1800  
Arlington, VA 22209  
USA

City: State: Zip:

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41)..... \$40

☒ Credit Card Payment form attached☐ Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gregory E. Montone, Reg# 28,141

June 20, 2003

Name of Person Signing

Signature

Date

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PATENT  
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**ASSIGNMENT**  
( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd.,  
a corporation organized under the laws of Japan,  
located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan,  
receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,  
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

**SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND METHOD FOR MANUFACTURING  
THE SAME**

invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,  
to be held and enjoyed by said Hitachi, Ltd.,  
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) <u>Akio Nishida</u> Akio NISHIDA	<u>17/February/2003</u>
2) <u>Yasuko Yoshida</u> Yasuko YOSHIDA	<u>20/February/2003</u>
3) <u>Shuji Ikeda</u> Shuji IKEDA	<u>20/February/2003</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____